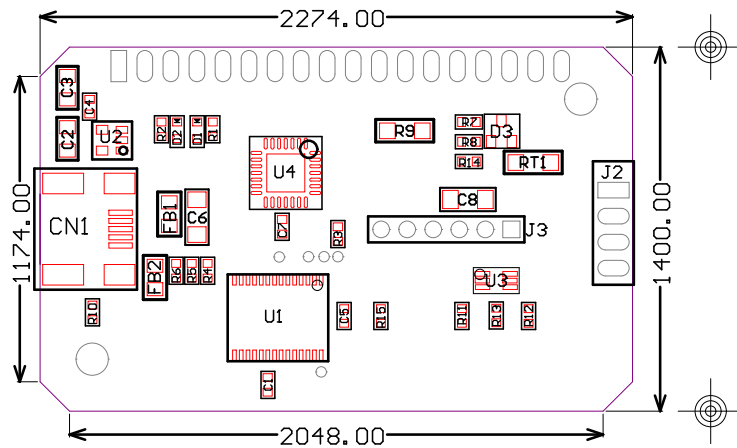



Top Assembly



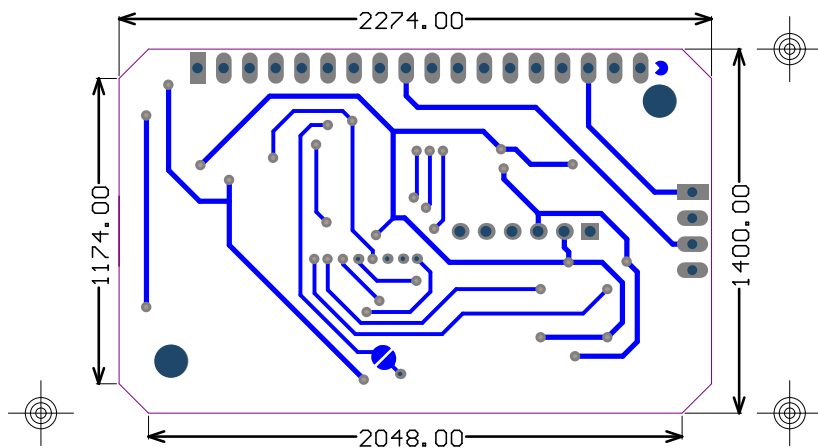
DS9400# Evaluation Kit				
Part Number: 89-94000#000				
 Property of maxim integrated				Rev B
Drill and Mechanical Layer				
Date: Dec 16 2011 Units in mils				
SIZE	QTY	SYM	PLATED	TOLERANCE
17	40		YES	+/- 0.003
35	2		NO	+/- 0.003
39	28		YES	+/- 0.003
128	2		NO	+/- 0.003


Fab Notes:

1. Material: FR-4 or similar laminate material
2. Board Dimensions = 2.274 x 1.400 mils
3. Board Thickness = 62 mils +/- 20%
4. Layers = 2
5. Minimum Trace Width = 6mil Trace Spacing = 6mil
6. Copper Thickness = 1oz on all layers
7. Surface mount pads = 137 BGA pads = 0
8. Through holes: Quantity = 72 minimum hole size = 17mil
9. Laser holes: Quantity = N/A minimum hole size = N/A
10. Soldermask= Green
11. Legend = White on Top only
12. Plating = Lead Free
13. Finish: Best finish option for lead free
14. Vendor Logo & date code = Allowed
15. Testing Needed = Yes
16. Tolerances:
 - Plated-through holes under BGA chips +/- N/A
 - All other plated-through holes +/- 0.003
 - Metal to Metal +/- 0.003
 - Legend to legend +/- no preference
 - Soldermask to Metal +/- 0.003

Layer Stack Up Detail for: DS9400R-B2.PcbDoc

Layer
Name



DS9400# Evaluation Kit					
Part Number: 89-94000#000					
<div>Property of maxim integrated</div>				Rev B	
Drill and Mechanical Layer					
Date: Dec 16 2011 Units in mils					
SIZE	QTY	SYM	PLATED	TOLERANCE	
17	40	*	YES	+/- 0.003	
35	2		NO	+/- 0.003	
39	28		YES	+/- 0.003	
128	2		NO	+/- 0.003	

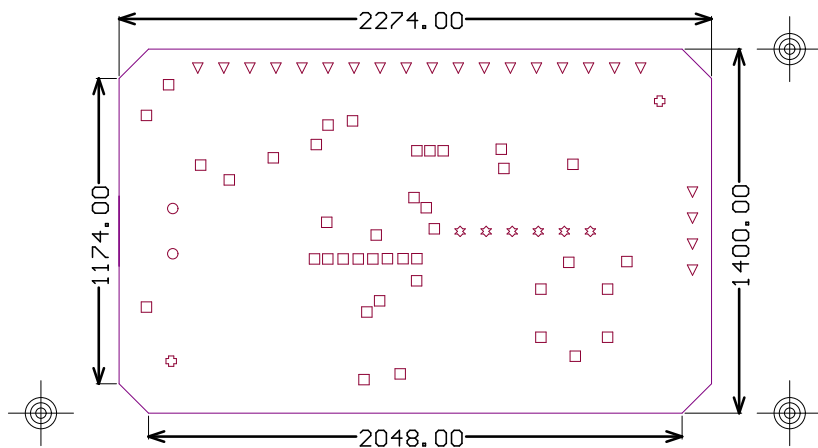
Fab Notes:


1. Material: FR-4 or similar laminate material
2. Board Dimensions = 2.274 x 1.400 mils
3. Board Thickness = 62 mils +/- 20%
4. Layers = 2
5. Minimum Trace Width = 6mil Trace Spacing = 6mil
6. Copper Thickness = 1oz on all layers
7. Surface mount pads = 137 BGA pads = 0
8. Through holes: Quantity = 72 minimum hole size = 17mil
9. Laser holes: Quantity = N/A minimum hole size = N/A
10. Soldermask= Green
11. Legend = White on Top only
12. Plating = Lead Free
13. Finish: Best finish option for lead free
14. Vendor Logo & date code = Allowed
15. Testing Needed = Yes
16. Tolerances:
 - Plated-through holes under BGA chips +/- N/A
 - All other plated-through holes +/- 0.003
 - Metal to Metal +/- 0.003
 - Legend to legend +/- no preference
 - Soldermask to Metal +/- 0.003

Layer Stack Up Detail for: DS9400R-B2.PcbDoc

Layer
Name

Bottom Layer



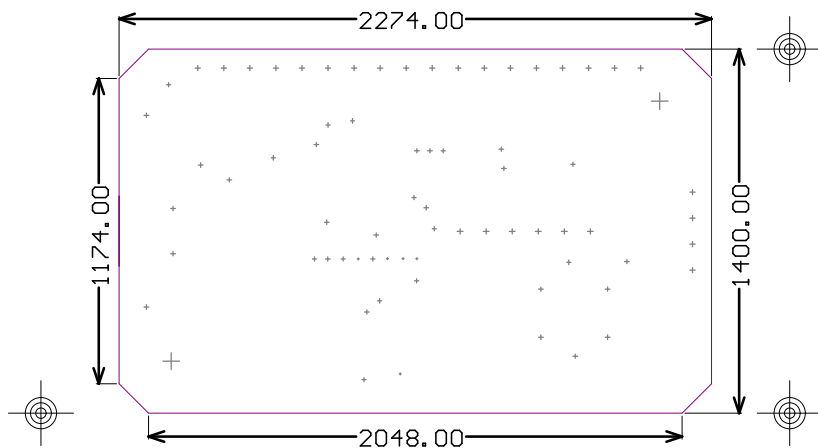
DS9400# Evaluation Kit				
Part Number: 89-94000#000				
<div></div> <div>Property of maxim integrated</div>			Rev B	
Drill and Mechanical Layer				
Date: Dec 16 2011 Units in mils				
SIZE	QTY	SYM	PLATED	TOLERANCE
17	40	□	YES	+/- 0.003
35	2	✕	NO	+/- 0.003
39	28	▽	YES	+/- 0.003
128	2	⊕	NO	+/- 0.003


Fab Notes:

1. Material: FR-4 or similar laminate material
2. Board Dimensions = 2.274 x 1.400 mils
3. Board Thickness = 62 mils +/- 20%
4. Layers = 2
5. Minimum Trace Width = 6mil Trace Spacing = 6mil
6. Copper Thickness = 1oz on all layers
7. Surface mount pads = 137 BGA pads = 0
8. Through holes: Quantity = 72 minimum hole size = 17mil
9. Laser holes: Quantity = N/A minimum hole size = N/A
10. Soldermask= Green
11. Legend = White on Top only
12. Plating = Lead Free
13. Finish: Best finish option for lead free
14. Vendor Logo & date code = Allowed
15. Testing Needed = Yes
16. Tolerances:
 - Plated-through holes under BGA chips +/- N/A
 - All other plated-through holes +/- 0.003
 - Metal to Metal +/- 0.003
 - Legend to legend +/- no preference
 - Soldermask to Metal +/- 0.003

Layer Stack Up Detail for: DS9400R-B2.PcbDoc

Layer Name



DS9400# Evaluation Kit					
Part Number: 89-94000#000					
<div>Property of maxim integrated</div>				Rev B	
Drill and Mechanical Layer					
Date: Dec 16 2011 Units in mils					
SIZE	QTY	SYM	PLATED	TOLERANCE	
17	40	+	YES	+/- 0.003	
35	2	+	NO	+/- 0.003	
39	28	+	YES	+/- 0.003	
128	2	+	NO	+/- 0.003	

Fab Notes:

1. Material: FR-4 or similar laminate material
2. Board Dimensions = 2.274 x 1.400 mils
3. Board Thickness = 62 mils +/- 20%
4. Layers = 2
5. Minimum Trace Width = 6mil Trace Spacing = 6mil
6. Copper Thickness = 1oz on all layers
7. Surface mount pads = 137 BGA pads = 0
8. Through holes: Quantity = 72 minimum hole size = 17mil
9. Laser holes: Quantity = N/A minimum hole size = N/A
10. Soldermask= Green
11. Legend = White on Top only
12. Plating = Lead Free
13. Finish: Best finish option for lead free
14. Vendor Logo & date code = Allowed
15. Testing Needed = Yes
16. Tolerances:
 - Plated-through holes under BGA chips +/- N/A
 - All other plated-through holes +/- 0.003
 - Metal to Metal +/- 0.003
 - Legend to legend +/- no preference
 - Soldermask to Metal +/- 0.003

Layer Stack Up Detail for: DS9400R-B2.PcbDoc

Layer Name